Design Notes
* Converter is working in discontinuous conduction mode
* Duty cycle is 30.62%
* R14 is necessary only for test purpose
* Built on PCB PMP8621 Rev.B
* Parts with RefDes >100 added (no footprint available)

You should completely validate and test your design implementation to confirm the system functionality for your application.

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You should completely validate and test your design implementation to confirm the system functionality for your application.

* C101..107: 100nF, 100V, X7R, 0805
* D1, D101..106: MMSD914, 100V, 200mA

Input
18..30V

Output
300V @ 10mA
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